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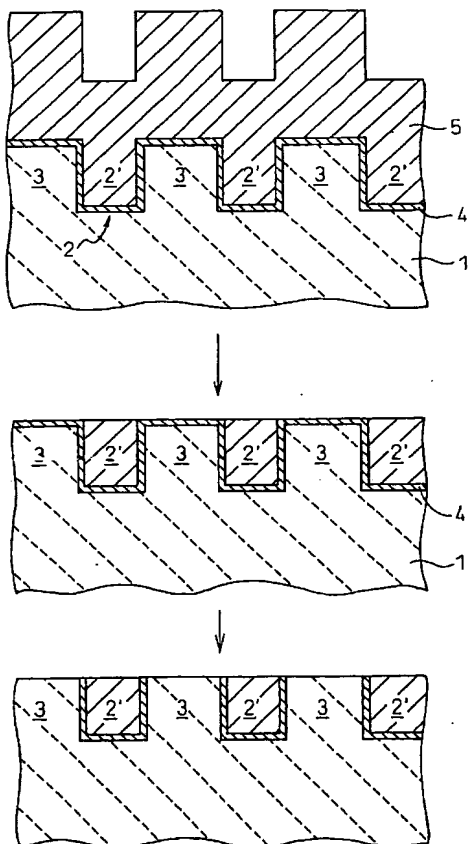
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(54) Title: POLISHING COMPOSITION AND POLISHING METHOD



(57) Abstract: To provide a polishing composition which allows high-speed polishing while etching and erosion are prevented and the flatness of metal film is maintained, there is provided a polishing composition, comprising (A) a compound having three or more azole moieties, (B) an oxidizing agent, and (C) one or more species selected from among an amino acid, an organic acid, and an inorganic acid.



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